PRODUCT DATA SHEET

InTACK®

Robust Tacking Agent for Integration with Heat-Spring®

Introduction

InTACK® is a thermally conductive tacking agent designed for use in compressible thermal interfaces where high reliability and low thermal resistance is a key requirement. **InTACK®** is dispensed to affix a Heat-Spring® or solder preform into position. Once in place, **InTACK®** reduces the thermal resistance of the compressed thermal interface it is used with. **InTACK®** assists with alignment and attachment to ICs in TIM2 applications or to burn-in test heads, providing a strong bond and extended working time, maintaining its tacking properties throughout the assembly process. It is suitable for use on a wide variety of metal surfaces. When applied with Heat-Spring® solder preforms, **InTACK®** offers a complimentary solution to manage the thermal performance of high power-density devices.

Features

- Reduces R^{th} of indium thermal interface material
- Not electrically conductive
- Maintains precise assembly alignment
- Compatible with Heat-Spring® and solder preforms
- Good workability
- Good adhesion to most metals, including Ag, Au, Cu, Ni, and Al
- Dispensing and jetting applications available

Properties

	Value	Test Method
Typical Viscosity	~10kcps	Brookfield HB DVII±CP
Typical Tackiness	~240g	J-STD-004A
Typical Acid Value	~0mg	KOH/g Titration
Thermal Conductivity with 0.012" Heat-Spring®	11W/m*K (compared to 9W/m*K without InTACK®)	Nanotest TIMA-5 according to ASTM D-5470
Shelf Life	12 months when stored between 0–30°C	Viscosity change/ microscope examination

All information is for reference only.
Not to be used as incoming product specifications.

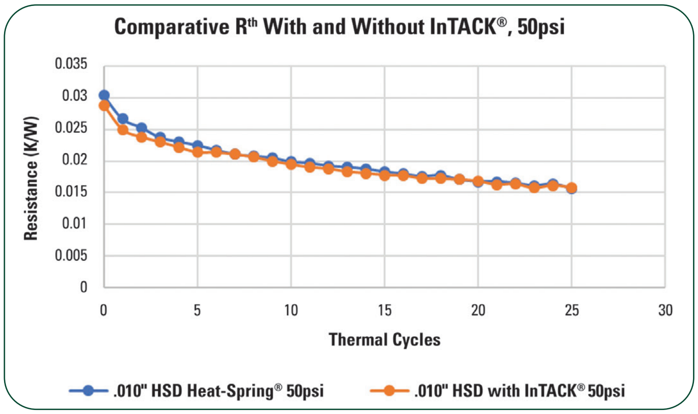
Packaging

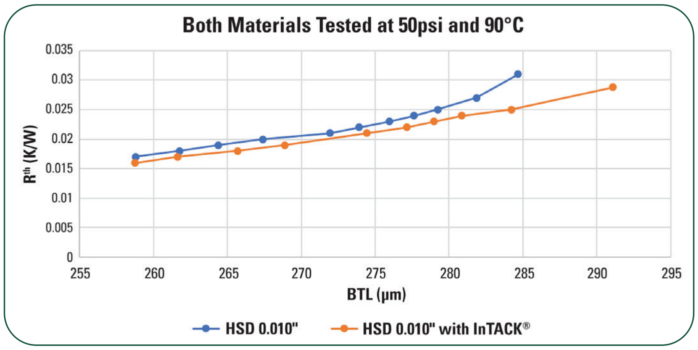
InTACK® is available in 10, 25, and 100g bottles, and 10 and 30cc syringes. Other packaging options may be available upon request.

Safety Data Sheets

Please refer to the SDS document within the product shipment, or contact our local team to receive a copy.

Thermal Performance





Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified.
Indium Corporation is an ISO 9001:2015 registered company.

From One Engineer To Another®

Contact our engineers: **askus@indium.com**
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